

Dual N-Channel MOSFET

General Description

The WSP8205 is the highest performance trench N-ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WSP8205 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

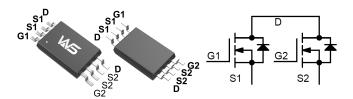
Product Summery

BVDSS	RDSON	ID
20V	20mΩ	6.0A

Applications

- High Frequency Point-of-Load Synchronous Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System

TSSOP-8 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V_{DS}	Drain-Source Voltage	20	V	
V_{GS}	Gate-Source Voltage	±12	V	
I _D @T _c =25℃	Continuous Drain Current, V _{GS} @ 4.5V ¹ 6.0			
I _D @T _c =70℃	Continuous Drain Current, V _{GS} @ 4.5V ¹	5.2	Α	
I _{DM}	Pulsed Drain Current ² 20		Α	
P _D @T _A =25°C	Total Power Dissipation ³ 1.25		W	
T _{STG}	Storage Temperature Range -55 to 150		$^{\circ}$	
TJ	Operating Junction Temperature Range -55 to 150		°C	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹		100	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		70	°C/W



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Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =250uA	20			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25℃, I _D =1mA		0.022		V/°C
		V _{GS} =10V , I _D =6A	16	20	27	
Passau		V_{GS} =4.5V , I_D =4A	19	23	30	
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =3.1V , I _D =4A	22	27	35	mΩ
		V_{GS} =2.5V , I_D =4A	25	30	39	
		V_{GS} =1.8V , I_D =2A	32	42	55	
$V_{GS(th)}$	Gate Threshold Voltage	\/ -\/ -250::A	0.4	0.7	1.0	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-2.33		mV/℃
	Desir Course Lealing Course	V_{DS} =16V , V_{GS} =0V , T_J =25 $^{\circ}$ C			1	uA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =16V , V _{GS} =0V , T _J =55℃			5	
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 12 V$, V_{DS} = $0 V$			±100	nA
gfs	Forward Transconductance	V_{DS} =5V , I_D =5A		25		S
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		4		Ω
Qg	Total Gate Charge (4.5V)			8.8	11.9	
Q _{gs}	Gate-Source Charge	V _{DS} =10V , V _{GS} =4.5V , I _D =6A		0.8	2.0	nC
Q _{gd}	Gate-Drain Charge			3.3	3.2	
T _{d(on)}	Turn-On Delay Time			5	10	
T _r	Rise Time	V_{DD} =10V , V_{GEN} =4.5V , R_G =6 Ω ,		15	26	ns
T _{d(off)}	Turn-Off Delay Time	I _D =1A ,R _L =10Ω.		30	55	
T _f	Fall Time			5	10	
C _{iss}	Input Capacitance			550		
C _{oss}	Output Capacitance	V _{DS} =10V , V _{GS} =0V , f=1MHz		100		pF
C _{rss}	Reverse Transfer Capacitance			85		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current ^{1,4}	V =V =0V Force Current			1.5	Α
I _{SM}	Pulsed Source Current ^{2,4}	V _G =V _D =0V , Force Current			20	Α
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1.5A , T _J =25℃			1.3	V
t _{rr}	Reverse Recovery Time			15		nS
Q _{rr}	Reverse Recovery Charge	lF=6A,dI/dt=100A/μs,T _J =25℃		7		nC

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, t≤10sec.
- 2.The data tested by pulsed , pulse width $\leq 300 \text{us}$, duty cycle $\leq 2\%$
- 4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



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Typical Characteristics

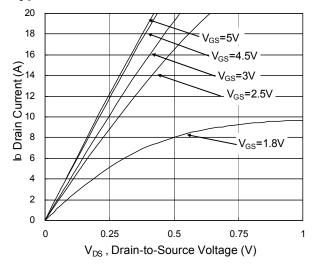
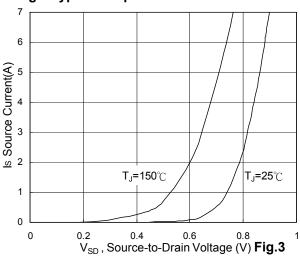


Fig.1 Typical Output Characteristics



Forward Characteristics Of Reverse

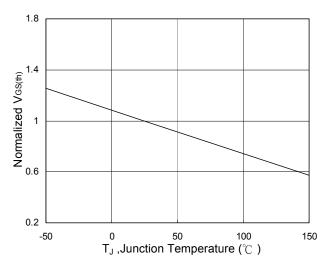


Fig.5 Normalized V_{GS(th)} vs. T_J

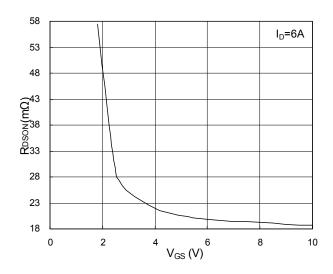


Fig.2 On-Resistance vs. Gate-Source

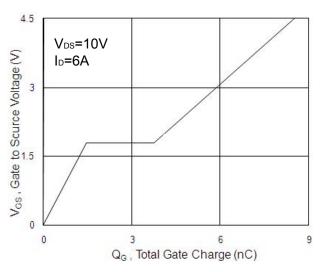


Fig.4 Gate-Charge Characteristics

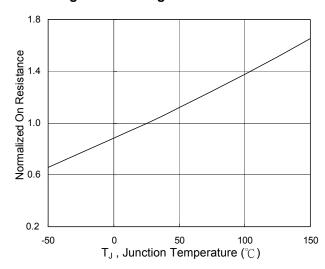
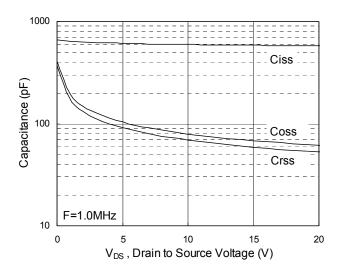


Fig.6 Normalized R_{DSON} vs. T_J







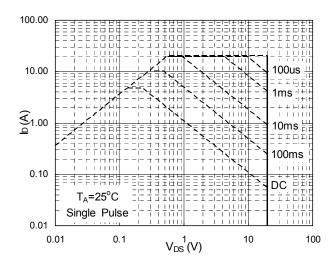


Fig.7 Capacitance

Fig.8 Safe Operating Area

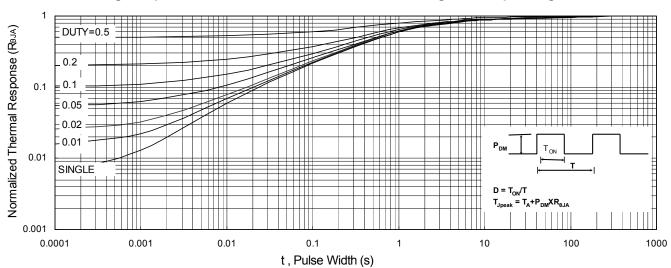


Fig.9 Normalized Maximum Transient Thermal Impedance

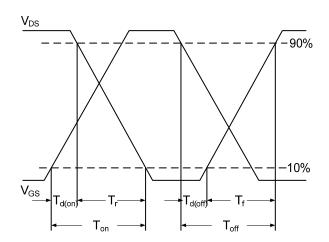


Fig.10 Switching Time Waveform

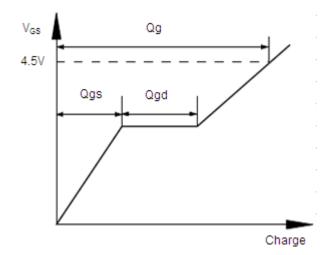


Fig.11 Gate Charge Waveform



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